# Product End-of-Life Disassembly Instructions

## Purpose:
The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cords Adapters</td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screw Driver</td>
<td>T8</td>
</tr>
<tr>
<td>Screw Driver</td>
<td>No.0</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Log-Door
2. Remove Battery
3. Remove HDD
4. Remove SC Holder
5. Remove Internal Frame
6. Remove Smart Card Module
7. Remove TP Module
8. Remove Speaker
9. Remove LED PCB
10. Remove Keyboard
11. Remove Thermal Module
12. Remove MB
13. Remove Speaker
14. Remove Log Up
15. Remove Bezel
16. Remove Hinge
17. Remove Panel
18. Remove Web Camera

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Step 1 Remove Log-Door
Step 2 Remove Battery
Step 3 Remove HDD
Step 4 Remove SC holder
Step 5 Remove Internal Frame
Step 6 Remove Smart Card Module

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
Step 7 Remove TP Module

Step 8 Remove Speaker

Step 9 Remove LED PCB

Step 10 Remove Keyboard

Step 11 Remove Thermal Module

Step 12 Remove MB

PSG instructions for this template are available at EL-MF877-01
Step 13 Remove Log Up

Step 14 Remove Bezel

Step 15 Remove Hinge

Step 16 Remove Panel

Step 17 Remove Hinge
3.21 Total part disassembly

3.22 Remove battery module

3.23 Remove service door

3.24 LCD module set disassembly

3.25 Top case disassembly

3.26 Thermal module and mother board disassembly

3.27 Bottom case disassembly